



**AI TECHNOLOGY INC**  
 70 Washington Road  
 Princeton Jct., NJ 08550  
 (609) 799-9388 fax (609) 799-9308  
 E-Mail: [ait@aitechnology.com](mailto:ait@aitechnology.com)  
 Internet: <http://www.aitechnology.com>

**Tacky, Non Curing**  
**Pressure Sensitive**  
**High Thermally Conductive**  
**Electrically Insulating**  
**Film Adhesive**

**IDEAL FOR:**

- Component Attach
- Heat Sink Attach
- Substrate Attach

**DESCRIPTION:**

TP7209 is a low bond strength thermoplastic film adhesive. It is designed for bonding heat-sink, component, and substrate. This unique diamond filled material has excellent thermal conductivity and is tacky at room temperature.

**AVAILABILITY:**

TP7209 is available in sheet sizes or as custom preforms. Standard thicknesses are 0.004" and 0.006". Special thicknesses are available. TP7209 can be obtained in liquid form (LTP7209). This product is fiber glass reinforced.

**APPLICATION PROCEDURES:**

- ( 1 ) Cut or pre-cut to desired size.
- ( 2 ) Remove one side of release paper from adhesive.
- ( 3 ) Place on substrate or component with rolling finger pressure, then remove the other release paper.
- ( 4 ) Place component on substrate with insertion pressure of 15 psi or more.

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

**THERMOPLASTIC FILM**  
**TP7209**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 25 °C/1 minute )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	-55 ±10%
Lap-Shear Strength	>100 psi >0.69 N/mm <sup>2</sup>
Device Push-off Strength	200 psi ±10% 1.4 N/mm <sup>2</sup> ±10%
Cured Density (gm/cc)	2.2 ±10%
Hardness (Type)	<40 ±10%
Thermal Conductivity	80 Btu-in/hr-ft <sup>2</sup> -°F ±10% 11.4 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	110 ±15%
Tensile Modulus:	
Maximum Continuous Operation Temp. (°C)	<150

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

Temperature	Time	Pressure
None		15 psi

**SHELF LIFE:**

Storage temperature	Shelf Life
25°C	1 yr